

FLEXIBLE HYBRID ELECTRONICS IMAGINE CREATE ACCOMPLISH

MICRO ASSEMBLY TECHNOLOGY

INKJET PRINTED ELECTRONICS

ADVANCED PACKAGING



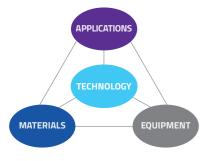
TECHNOLOGY FOR FLEXIBLE HYBRID ELECTRONICS & MICRO ASSEMBLY

OUR MISSION

Driven by the growing interconnected world, the demand for integrated and wireless electronic functionality is increasing. Beyond conventional and rigid PCBA's, innovative printing technology, IC integration and advanced packaging are creating new possibilities to embed and assimilate electronics in products.

DoMicro embarks upon the business opportunities this brings. We do this using our expertise in innovative inkjet and nanowire printing, IC integration and advanced packaging for applications in wearables, IoT, healthcare and sensor applications.

Supported with contract research, technology consultancy and the development of prototypes, this will bring your ideas from an innovative technology into use for your applications, equipment, and materials.



Our approach is agile, flexible and dedicated. Let's cross boundaries together. Our dedicated and flexible team invites you.

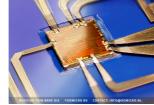
Do it 'Do Micro'.

Samples

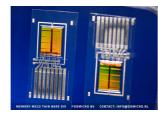
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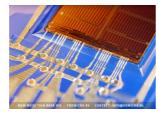






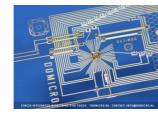








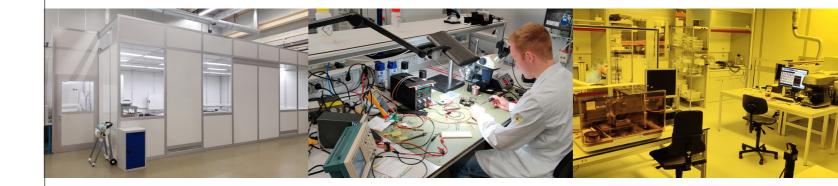






AUTOMOTIVE / SMART LIVING / SMART MOBILITY / SEMICONDUCTORS / HIGH TECH INDUSTRY /

OUR SERVICES



Realising opportunities in the industry is best done in a structured approach. We therefore offer contract research, technology consultancy, development of prototypes and project management for five subsequent steps:

Demonstrating feasibility

Realising functionality

Proving reliability Demonstrating capability

Preparing productivity

We support all five steps or, depending on the customer needs, a selection of them.

The technology areas include inkjet printing, pre- and post-processing, materials, integration, recipes, quality control, 3D packaging, micro assembly, pick & place, interconnections and nanowires.



ABOUT US

DoMicro BV is a technology company providing innovative manufacturing technology, application solutions and micro assembly technology for flexible hybrid electronics (FHE) and micro devices. DoMicro excels in developing cutting edge inkjet printing processes, micro assembly and 3D packaging technology.

As a technology provider, we support research institutes, SMEs and multinationals with contract research, technology consultancy, the development of prototypes and project management. Typically this is done for customers exploring new technologies for circuitry on flexible substrates like transparent conductive films, OPV electrodes, OLED, Lab-on-chip, wearables, inmold electronics, IC and MEMS integrations.

The track record is with international customers in

the automotive sector and the high-tech industry. Furthermore, we participate as a partner in international innovation projects. We typically are the pioneers and technology scouts in our projects, with a 'can do" mentality. Our drive is to help with a quick materialization of the customer vision by making ambitions concrete in an excellent engineering approach.

Our ISO7 cleanroom infrastructure and network in high tech industry provide excellent conditions to enable results. In our micro assembly lab, we have amongst others inkjet printers, a nanowire printer, a screen printer, a die bonder, a wire bonder and microscopes.

If you are challenged by the market and looking for a partner to move your ideas into realization, contact us. We really do IMAGINE, CREATE AND ACCOMPLISH.



Automotive Inmould



Flexible
Electronics
Printing



MedTech Micro Fluidics



Wearables



Semicon Micro Assembly



SOLAR



PCBAPrinting



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